



THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Hideki Tanaka

Serial No.: 09/788,503

Group Art Unit: 2823

Filed: February 21, 2001

Examiner: Nguyen, Khiem D.

For: TAPE CARRIER TYPE SEMICONDUCTOR DEVICE, METHOD FOR  
MANUFACTURING THE SAME, AND FLEXIBLE SUBSTRATE

Honorable Commissioner of Patents  
Washington, D.C. 20231

#7/a  
RECEIVED  
JAN 10 2003  
TECHNOLOGY CENTER 2800  
1-17-03  
L. Spruell

Lee OK

**AMENDMENT UNDER 37 C.F.R. §1.111**

Sir:

In response to the Office Action dated **October 8, 2002**, please amend the above-  
identified application as follows:

**IN THE CLAIMS:**

**Please cancel claim 12 without prejudice or disclaimer.**

**Please amend the following claims:**

1. (Amended) A tape carrier type semiconductor device comprising:

a flexible substrate on whose surface wiring is formed; and

a driver circuit which is mounted on said flexible substrate and drives a device  
connected to said flexible substrate,

wherein said flexible substrate includes a first slit having a connector situated  
intermediate thereto for connecting both sides of the first slit to reduce warpage, and

wherein said first slit comprises a first sub-slit and a second sub-slit with said  
connector therebetween.

01/09/2003 WRBDELRI 00000092 09788503 108.00 DP  
01 FC:1202